Amendments to the Claims:

Please amend Claim 23 and add new Claims 27-31 as follows.

1. to 22. (Cancelled)

23. (Currently Amended) A wiring forming method comprising:

a first step of supplying a first liquid containing an insulating material on a substrate to form an insulated pattern on the substrate, the first insulated pattern partially forming a first layer in a single plane;

a second step of, after the first step, supplying a second liquid containing a conductive material on the substrate to form a first conductive pattern, the first conductive pattern partially forming the first layer in the single plane;

a third step of, after the second step, applying the second liquid on the first conductive pattern to form a plurality of through hole portions on the first conductive pattern, the plurality of through hole portions partially forming a second layer;

a fourth step of, after the third step, applying the first liquid on the first layer that the first insulated pattern and the first conductive pattern have formed to form a second insulated pattern as part of the second layer that the plurality of through hole portions partially formed; and

a fifth step of, after the fourth step, forming a part of a third layer by supplying the second liquid on the second layer so as to connect the plurality of through hole portions.

24. (Previously Presented) The wiring forming method according to claim 23, wherein the first insulated pattern and the first conductive pattern are formed so that they come into contact with each other.

25. (Previously Presented) The wiring forming method according to claim 23, wherein the first liquid and the second liquid are supplied by using an ink jet system.

26. (Previously Presented) The wiring forming method according to claim 23, further comprising a sixth step, after the fourth step, of forming a part of a third layer by supplying the first liquid on the second layer.

27. (New) The wiring forming method according to claim 23, wherein the second layer is formed in a single layer.

28. (New) A wiring forming method comprising:

a first step of supplying a first liquid containing an insulating material in a single plane on a substrate to form an insulated pattern on the substrate, the first insulated pattern partially forming a first layer;

a second step of, after the first step, supplying a second liquid containing a conductive material in a single plane on the substrate to form a first conductive pattern, the first conductive pattern partially forming the first layer;

a third step of, after the second step, applying the second liquid on the first conductive pattern to form a plurality of through hole portions on the first conductive pattern, the plurality of through hole portions partially forming a second layer;

a fourth step of, after the third step, applying the first liquid on the first layer that the first insulated pattern and the first conductive pattern have formed to form a second insulated pattern as part of the second layer that the plurality of through hole portions partially formed; and

a fifth step of, after the fourth step, forming a part of a third layer by supplying the second liquid on the second layer so as to connect the plurality of through hole portions.

29. (New) The wiring forming method according to claim 28, wherein the first insulated pattern and the first conductive pattern are formed so that they come into contact with each other.

30. (New) The wiring forming method according to claim 28, wherein the first liquid and the second liquid are supplied by using an ink jet system.

31. (New) The wiring forming method according to claim 28, further comprising a sixth step, after the fourth step, of forming a part of a third layer by supplying the first liquid on the second layer.